



# Material Composition Declaration

## EPC21601

Company Name	Efficient Power Conversion (EPC)	Issue Date:	7/6/2022
Contact Name:	Yanping Ma	Contact Title:	VP Quality
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Part Weight:	2.0 mg	Type of Product:	eGaN IC

Construction Element	Substance	CAS No. If Applicable	Weight	Mass	Sum	Mass
			(mg)	(%)	(%)	(ppm)
Chip	Silicon	7440-21-3	1.5975	78.5822	81.1506	785822
	Silicon oxide	7631-86-9	0.0060	0.2927		2927
	Silicon nitride	12033-89-5	0.0023	0.1135		1135
	Gallium nitride	25617-97-4	0.0103	0.5047		5047
	Aluminum	7429-90-5	0.0118	0.5806		5806
	Aluminum nitride	24304-00-5	0.0025	0.1210		1210
	Titanium	7440-32-6	0.0004	0.0213		213
	Titanium nitride	25583-20-4	0.0018	0.0868		868
	Copper	7440-50-8	0.0002	0.0097		97
	Tungsten	7440-33-7	0.0029	0.1426		1426
	Polyimide		0.0141	0.6955	6955	
Under Bump Metal	Titanium	7440-32-6	0.0002	0.0106	0.8938	106
	Copper	7440-50-8	0.0180	0.8832		8832
Solder Bump	Tin	7440-31-5	0.3486	17.1476	17.9556	171476
	Silver	7440-22-4	0.0146	0.7182		7182
	Copper	7440-50-8	0.0018	0.0898		898
Sum in total:			2.0329	100.0000	100.0000	1000000

**Note:**

The substance content disclosed herewith is approximate and is based on engineering calculation. Statements are based on our present knowledge and may subject to change at any time due to technical requirements and development. EPC may update this document without notification. Statement may not include information regarding the minute quantities of dopant and metal materials in the electrical devices contained within the finished product.